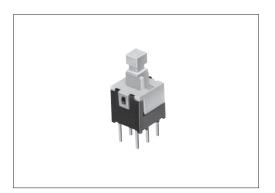
# 1mm short travel



# ■ Typical Specifications

Ite	ms	Specifications		
Rating (max.)/(mi (Resistive load)	n.)	0.1A 12V DC / 50μA 3V DC		
Contact resistand (Initial/ After oper	-	$30$ m $\Omega$ max. / $50$ m $\Omega$ max.		
Operating force		2±1N		
Operating life	Without load	10,000 cycles		
Operating me	With load	10,000 cycles (0.1A 12V DC)		

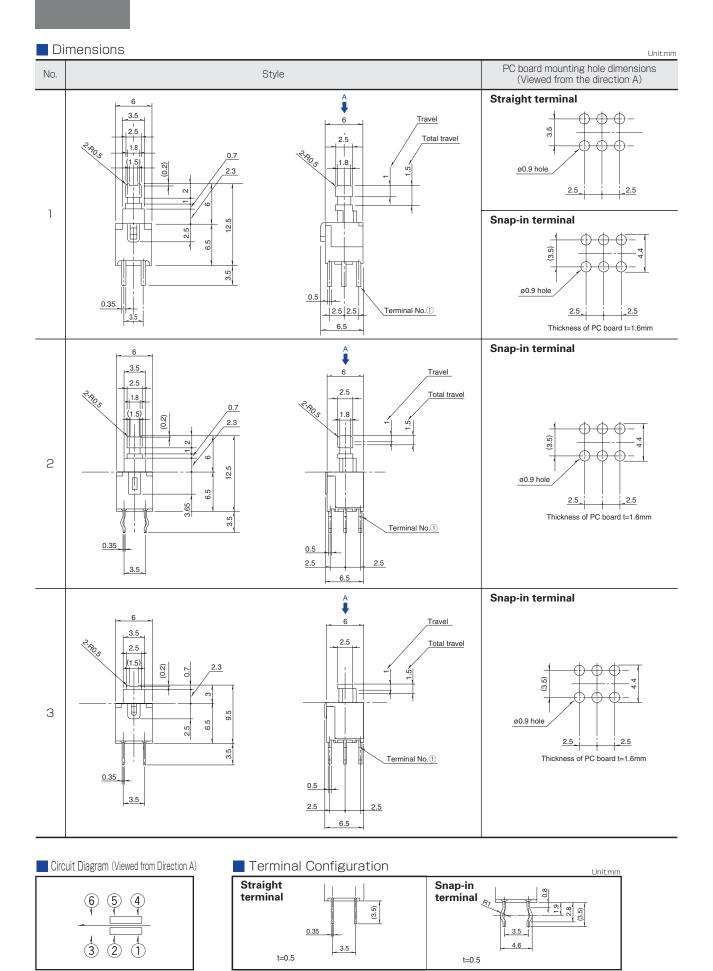
## Product Line

Changeover timing	Travel (mm)	Total travel (mm)	Mounting method	Poles	Knob style	Operation	Terminal type	Minimum order unit (pcs.)  Japan Export		Product No.	Drawing No.
Non shorting 1 1.5				Standard Latching  Latching	Otrocialet		SPPH210100	,			
		15 DC board			Momentary	Straight	100	100 10,000	SPPH210500	'	
	1 1.5 PC board		2		Latching				SPPH260100	2	
		1 -		Momentary	Snap-in	100	10,000		SPPH230500	1	
				Short	Latching	Oriap-iri	Зпар-ш		SPPH240100	3	
						OI IOI L	Momentary				SPPH240300

# Packing Specifications

Bulk

Number of pa	ckages (pcs.)	Export package measurements		
1 case / Japan 1 case / export packing		(mm)		
2,000	10,000	400×270×290		





			Vertical								
	Series		SPEH	SPEG	SPEJ	SPPH2	SPPH4	SPPH1			
Photo											
W		W	6	7.19	7	6	6.5	10			
Dimensio (mm)	ons D		6	8.39	7	6.5	8.5	10			
		Н	5	3.5	5.95	6.5	8	.5			
Tra	vel (mm)	)	_	_	1.7	1	2.2	1.5			
Total	travel (m	ım)	1.6	1.1	1.7	1.5	3	2.5			
Numb	per of pol	es	1	1	2		2				
	perating rature ra	nge	-40℃ to +90℃	-10°C to +60°C	-40℃ to +85℃		-10°C to +60°C				
Auto	motive u	se	•	_	•	_	_	•			
Li	fe cycle		<b>*</b> 3	<b>*</b> 3	*3	*3		<b>*</b> 3			
	ng (max istive loa		50mA 16V DC	1mA 5V DC	0.2A 14V DC	0.1A 12V DC 0.1A 30V E		OV DC			
	ing (min. istive loa		10μA 1V DC	50μA 3V DC	_	50μA 3V DC					
D. white		ting life ut load	100,000 cycles 400mΩ max.	30,000 cycles 500mΩ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.			
Durability		life with load rated load)	100,000 cycles 400mΩ max.	30,000 cycles 500mΩ max.	10,000 cycles 150mΩ max.	10,000 cycles 50mΩ max.	10,000 cycles 100mΩ max.	10,000 cycles 40mΩ max.			
		contact tance	200mΩ max.	200mΩ max.	150mΩ max.	30mΩ max. 100mΩ m		20mΩ max.			
Electrical performance		lation tance	100MΩ min. 100V DC	3MΩ min. 100V DC	100MΩ min. 500V DC	100MΩ min. 500V DC		)C			
	Voltag	ge proof	250V AC for 1minute	100V AC for 1minute	500V AC for 1minute	500V AC for 1minute		е			
		minal ength	_	0.5N for 1minute	_	5N for 1minute					
Mechanical performance	Actuator strength	Operating direction	50	DN	49N	49N 30N		50N			
		strength		_	_	_	_	10N	_		
	Cold		-40°C 1,000h	-20°C 96h	-40℃ 500h	-20°C 96h					
Environmental performance	Dry heat		90°C 1,000h	85℃ 96h	85°C 500h	85°C 96h					
	Damı	o heat	60°C, 90 to 95% RH 1,000h	40°C, 90 to 95% RH 96h	60°C, 90 to 95% RH 500h	40°C,90 to 95%RH 96h					
	Page		124	125	126	127	129	130			

### Note

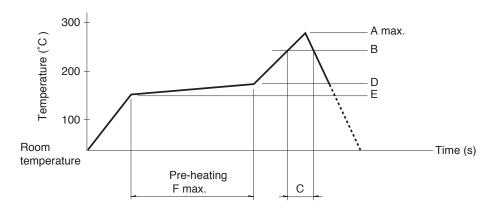
• Indicates applicability to all products in the series.



# Push Switches Soldering Conditions

### Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.
- 3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (°C)	E (℃)	F(s)
SPEG						
SPEJ	260	230	40	180	150	120
SPEF						
SPEH						

### Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

### Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±10℃	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10℃	4s max.	
SPEG, SPEF	350±5℃	3s max.	
SPEH, SPPH2	350°C max.	3s max.	
SPUJ	300±10°C	3+1/0s	

### Reference for Dip Soldering (For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100℃ max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

